# Product End-of-Life Disassembly Instructions

**Product Category:** External Options Monitor and Display

**Marketing Name / Model**
[List multiple models if applicable.]

| HP McCuller E23 G4 Display |

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPI products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

**NOTE:** Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking, please contact HP’s Sustainability Contact.

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm IF BD, Power BD, USB side board</td>
<td>3</td>
</tr>
<tr>
<td>Batteries, excluding Li-Ion batteries.</td>
<td>All types including standard alkaline, coin or button style batteries</td>
<td>0</td>
</tr>
<tr>
<td>Li-Ion batteries. Include all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, RTC coin cell, etc.)</td>
<td>Battery(ies) are attached to the product by (check all that apply with an “x” inside the “[ ]”): [ ] screws [ ] snaps [ ] adhesive [ ] other. Explain _____</td>
<td></td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps Panel</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>AC power cord, HDMI cable, DP cable, USB cable</td>
<td>4</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>

HPI instructions for this template are available at [EL-MF877-01](#)
<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing radioactive substances</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1</td>
<td>SCREW DRIVER(PHILLIPS HEAD)</td>
</tr>
<tr>
<td>Description #2</td>
<td>SCREW DRIVER(HEX HEAD)</td>
</tr>
<tr>
<td>Description #3</td>
<td>SCREW DRIVER(PHILLIPS HEAD)</td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure:

1. Remove Cable From Display Head
2. Remove Stand Base From Display Head
3. Remove Rear Cover From Display Head
4. Disassemble Rear Cover
5. Remove Bracket Assembly From Display Head
6. Remove Middle Cover From Display Head
7. Disassemble Bracket Assembly
8. Disassemble Stand Assembly
9. Disassemble Panel Assembly

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
1. Remove cable from display head

1. Remove cable from display head
2. Remove Stand Base From Display Head

2.1 Push the release button
2.2 Pull the stand

2.3 Remove stand base assembly
3. Remove Rear Cover From Display Head

Release the four screws from rear cover

Pull the rear cover

#2 cross screwdriver
4. Discassemble Rear Cover

4.1 Release the two screws from rear cover
4.2 Remove USB BD
4.3 Remove OSD BD

#2 cross screwdriver
4. Disassemble Rear-cover Assembly

4.4 Release the two screws from rear cover

4.5 Remove OSD KEY
4.6 Remove speaker cover

4.7 Remove release button

#2 cross screwdriver
5. Remove Bracket Assembly From Display Head

5.1 Remove all inside cable

5.2 Remove Bracket Assembly
6. Remove Middle Cover From Display Head

6.1 Release all the screws

6.2 Remove middle cover

#2 cross screwdriver
7. Disassemble Bracket Assembly

7.1 Remove black Mylar
7. Disassemble Bracket Assembly

7.2 Release the two VGA screws from bracket
7.3 Release the five screws from BD
7.4 Remove interface and power BD

#2 cross screwdriver
7. Disassemble Bracket Assembly

7.5 Remove EMI gaskets and Mylar
8. Disassemble Stand Assembly

1. Release the two thumb screws

2. Release the base

3. Remove base from stand

4. Release four screws from stand
8. Disassemble Stand Assembly

5. Remove the swivel

6. Release the six screws

7. Remove the swivel cover from stand

#2 cross screwdriver
8. Disassemble Base Assembly

8. Release the four screws

9. Remove the VESA plate

10. Release the four screws

11. Remove the pivot cover

#2 cross screwdriver
8. Disassemble Stand Assembly

12. Remove the tilt cover and riser cover

13. Remove all part

14. Release the three screws

15. Remove all part
9. Disassemble Panel Assembly

01. Back side Shielding disassembly

Use cross screwdriver to unlock the three screws

cross screwdriver #1
9. Disassemble Panel Assembly

02. Back side Source board disassembly

Lift up the source board that stick by double tape
9. Disassemble Panel Assembly

03. Front side OC disassembly

Use film to separate the OC and MF

Note: there will be residual gum on the OC and MF. It is easy to tear off by hand. (as next page)
9. Disassemble Panel Assembly

residual gum on OC

residual gum on MF
9. Disassemble Panel Assembly

4. Front side middle frame disassembly

loose all the hooks by hand
9. Disassemble Panel Assembly

05. Take out 3pcs film

Note: use hand to carry the suspension loop left and right side to take out the film.
9. Disassemble Panel Assembly

06. Take out LGP

*note*: use hand to hold the two sides when take out LGP

Use tape to stick one bottom corner of the LGP, then take it out.
9. Disassemble Panel Assembly

07. Take out reflector

Use tape to stick one bottom corner of the reflector plate, then take it out.
9. Disassemble Panel Assembly

08. Take out light bar

-use knife to separate light bar and BC then take out light bar

note: Light bar can’t be reused after take out
Thank You !!!